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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	832
Number of Logic Elements/Cells	8320
Total RAM Bits	106496
Number of I/O	382
Number of Gates	526000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k200fc484-2v

General Description

APEX™ 20K devices are the first PLDs designed with the MultiCore architecture, which combines the strengths of LUT-based and product-term-based devices with an enhanced memory structure. LUT-based logic provides optimized performance and efficiency for data-path, register-intensive, mathematical, or digital signal processing (DSP) designs. Product-term-based logic is optimized for complex combinatorial paths, such as complex state machines. LUT- and product-term-based logic combined with memory functions and a wide variety of MegaCore and AMPP functions make the APEX 20K device architecture uniquely suited for system-on-a-programmable-chip designs. Applications historically requiring a combination of LUT-, product-term-, and memory-based devices can now be integrated into one APEX 20K device.

APEX 20KE devices are a superset of APEX 20K devices and include additional features such as advanced I/O standard support, CAM, additional global clocks, and enhanced ClockLock clock circuitry. In addition, APEX 20KE devices extend the APEX 20K family to 1.5 million gates. APEX 20KE devices are denoted with an “E” suffix in the device name (e.g., the EP20K1000E device is an APEX 20KE device). [Table 8](#) compares the features included in APEX 20K and APEX 20KE devices.

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

Normal Mode

The normal mode is suitable for general logic applications, combinatorial functions, or wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a four-input LUT. The Quartus II software Compiler automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. LEs in normal mode support packed registers.

Arithmetic Mode

The arithmetic mode is ideal for implementing adders, accumulators, and comparators. An LE in arithmetic mode uses two 3-input LUTs. One LUT computes a three-input function; the other generates a carry output. As shown in [Figure 8](#), the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, when implementing an adder, this output is the sum of three signals: DATA1, DATA2, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

The Quartus II software implements parameterized functions that use the arithmetic mode automatically where appropriate; the designer does not need to specify how the carry chain will be used.

Counter Mode

The counter mode offers clock enable, counter enable, synchronous up/down control, synchronous clear, and synchronous load options. The counter enable and synchronous up/down control signals are generated from the data inputs of the LAB local interconnect. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. Consequently, if any of the LEs in an LAB use the counter mode, other LEs in that LAB must be used as part of the same counter or be used for a combinatorial function. The Quartus II software automatically places any registers that are not used by the counter into other LABs.

The counter mode uses two three-input LUTs: one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load overrides any signal carried on the cascade chain. The synchronous clear overrides the synchronous load. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

Clear & Preset Logic Control

Logic for the register's clear and preset signals is controlled by LAB-wide signals. The LE directly supports an asynchronous clear function. The Quartus II software Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset. Moreover, the Quartus II software Compiler can use a programmable NOT-gate push-back technique to emulate simultaneous preset and clear or asynchronous load. However, this technique uses three additional LEs per register. All emulation is performed automatically when the design is compiled. Registers that emulate simultaneous preset and load will enter an unknown state upon power-up or when the chip-wide reset is asserted.

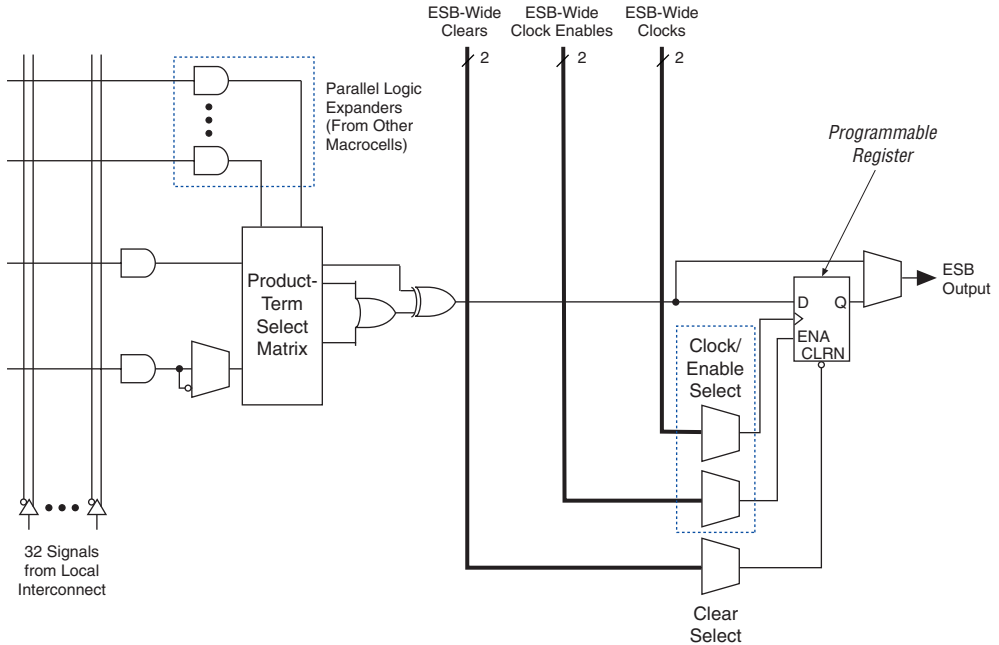
In addition to the two clear and preset modes, APEX 20K devices provide a chip-wide reset pin (`DEV_CLRn`) that resets all registers in the device. Use of this pin is controlled through an option in the Quartus II software that is set before compilation. The chip-wide reset overrides all other control signals. Registers using an asynchronous preset are preset when the chip-wide reset is asserted; this effect results from the inversion technique used to implement the asynchronous preset.

FastTrack Interconnect

In the APEX 20K architecture, connections between LEs, ESBs, and I/O pins are provided by the FastTrack Interconnect. The FastTrack Interconnect is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. The row interconnect routes signals throughout a row of MegaLAB structures; the column interconnect routes signals throughout a column of MegaLAB structures. When using the row and column interconnect, an LE, IOE, or ESB can drive any other LE, IOE, or ESB in a device. See [Figure 9](#).

Figure 14. APEX 20K Macrocell



For registered functions, each macrocell register can be programmed individually to implement D, T, JK, or SR operation with programmable clock control. The register can be bypassed for combinatorial operation. During design entry, the designer specifies the desired register type; the Quartus II software then selects the most efficient register operation for each registered function to optimize resource utilization. The Quartus II software or other synthesis tools can also select the most efficient register operation automatically when synthesizing HDL designs.

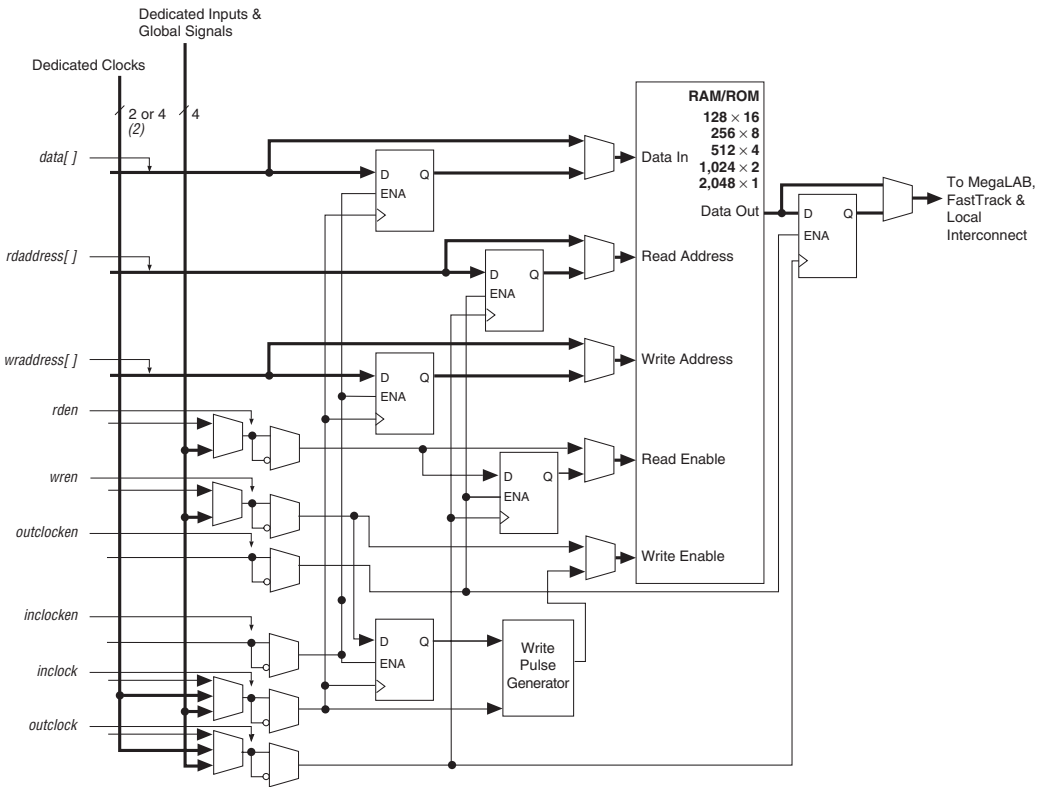
Each programmable register can be clocked by one of two ESB-wide clocks. The ESB-wide clocks can be generated from device dedicated clock pins, global signals, or local interconnect. Each clock also has an associated clock enable, generated from the local interconnect. The clock and clock enable signals are related for a particular ESB; any macrocell using a clock also uses the associated clock enable.

If both the rising and falling edges of a clock are used in an ESB, both ESB-wide clock signals are used.

Read/Write Clock Mode

The read/write clock mode contains two clocks. One clock controls all registers associated with writing: data input, WE, and write address. The other clock controls all registers associated with reading: read enable (RE), read address, and data output. The ESB also supports clock enable and asynchronous clear signals; these signals also control the read and write registers independently. Read/write clock mode is commonly used for applications where reads and writes occur at different system frequencies. Figure 20 shows the ESB in read/write clock mode.

Figure 20. ESB in Read/Write Clock Mode Note (1)

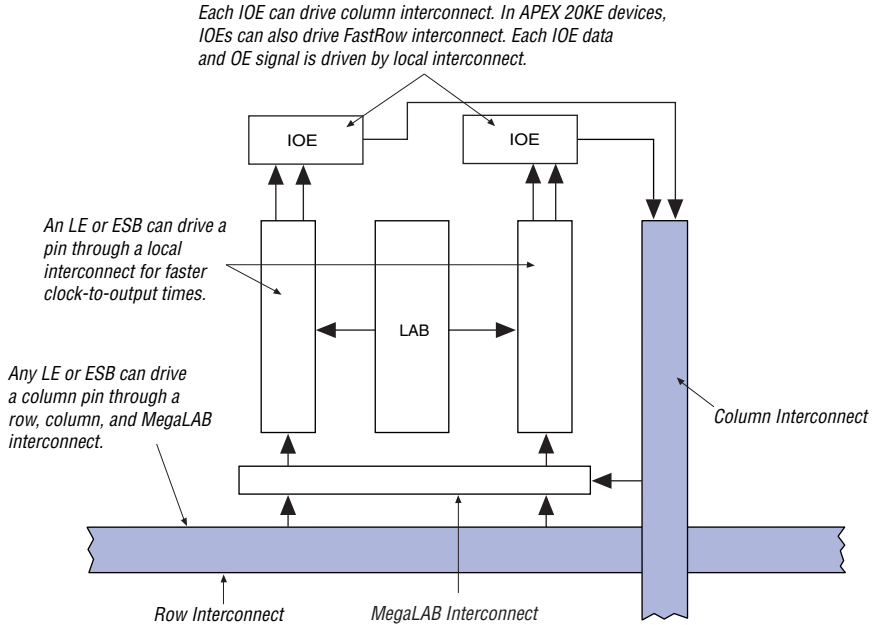


Notes to Figure 20:

- (1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.
- (2) APEX 20KE devices have four dedicated clocks.

Figure 28 shows how a column IOE connects to the interconnect.

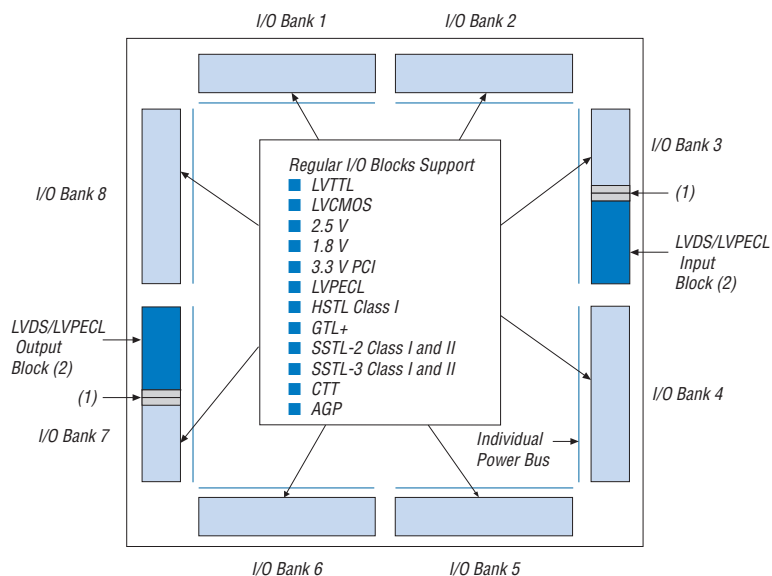
Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Figure 29. APEX 20KE I/O Banks



Notes to Figure 29:

- (1) For more information on placing I/O pins in LVDS blocks, refer to the *Guidelines for Using LVDS Blocks* section in *Application Note 120 (Using LVDS in APEX 20KE Devices)*.
- (2) If the LVDS input and output blocks are not used for LVDS, they can support all of the I/O standards and can be used as input, output, or bidirectional pins with V_{CCIO} set to 3.3 V, 2.5 V, or 1.8 V.

Power Sequencing & Hot Socketing

Because APEX 20K and APEX 20KE devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. Therefore, the V_{CCIO} and V_{CCINT} power supplies may be powered in any order.



For more information, please refer to the “Power Sequencing Considerations” section in the *Configuring APEX 20KE & APEX 20KC Devices* chapter of the *Configuration Devices Handbook*.

Signals can be driven into APEX 20K devices before and during power-up without damaging the device. In addition, APEX 20K devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20K and APEX 20KE devices operate as specified by the user.

MultiVolt I/O Interface

Under hot socketing conditions, APEX 20KE devices will not sustain any damage, but the I/O pins will drive out.

The APEX device architecture supports the MultiVolt I/O interface feature, which allows APEX devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The APEX 20K VCCINT pins must always be connected to a 2.5 V power supply. With a 2.5-V VCCINT level, input pins are 2.5-V, 3.3-V, and 5.0-V tolerant. The VCCIO pins can be connected to either a 2.5-V or 3.3-V power supply, depending on the output requirements. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and is compatible with 3.3-V or 5.0-V systems.

Table 12 summarizes 5.0-V tolerant APEX 20K MultiVolt I/O support.

V _{CCIO} (V)	Input Signals (V)			Output Signals (V)		
	2.5	3.3	5.0	2.5	3.3	5.0
2.5	✓	✓(1)	✓(1)	✓		
3.3	✓	✓	✓(1)	✓(2)	✓	✓

Notes to Table 12:

- (1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}.
- (2) When V_{CCIO} = 3.3 V, an APEX 20K device can drive a 2.5-V device with 3.3-V tolerant inputs.

Open-drain output pins on 5.0-V tolerant APEX 20K devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. When the pin is inactive, the trace will be pulled up to 5.0 V by the resistor. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

Table 18. APEX 20KE Clock Input & Output Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	I/O Standard	-1X Speed Grade		-2X Speed Grade		Units
			Min	Max	Min	Max	
f_{VCO} (4)	Voltage controlled oscillator operating range		200	500	200	500	MHz
f_{CLOCK0}	Clock0 PLL output frequency for internal use		1.5	335	1.5	200	MHz
f_{CLOCK1}	Clock1 PLL output frequency for internal use		20	335	20	200	MHz
f_{CLOCK0_EXT}	Output clock frequency for external clock0 output	3.3-V LVTTTL	1.5	245	1.5	226	MHz
		2.5-V LVTTTL	1.5	234	1.5	221	MHz
		1.8-V LVTTTL	1.5	223	1.5	216	MHz
		GTL+	1.5	205	1.5	193	MHz
		SSTL-2 Class I	1.5	158	1.5	157	MHz
		SSTL-2 Class II	1.5	142	1.5	142	MHz
		SSTL-3 Class I	1.5	166	1.5	162	MHz
		SSTL-3 Class II	1.5	149	1.5	146	MHz
		LVDS	1.5	420	1.5	350	MHz
f_{CLOCK1_EXT}	Output clock frequency for external clock1 output	3.3-V LVTTTL	20	245	20	226	MHz
		2.5-V LVTTTL	20	234	20	221	MHz
		1.8-V LVTTTL	20	223	20	216	MHz
		GTL+	20	205	20	193	MHz
		SSTL-2 Class I	20	158	20	157	MHz
		SSTL-2 Class II	20	142	20	142	MHz
		SSTL-3 Class I	20	166	20	162	MHz
		SSTL-3 Class II	20	149	20	146	MHz
		LVDS	20	420	20	350	MHz

Figure 32. APEX 20K AC Test Conditions *Note (1)*



Note to Figure 32:

- (1) Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast-ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result.

Operating Conditions

Tables 23 through 26 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 2.5-V APEX 20K devices.

Table 23. APEX 20K 5.0-V Tolerant Device Absolute Maximum Ratings *Notes (1), (2)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage	With respect to ground (3)	-0.5	3.6	V
V_{CCIO}			-0.5	4.6	V
V_I			-2.0	5.75	V
I_{OUT}	DC output current, per pin		-25	25	mA
T_{STG}	Storage temperature	No bias	-65	150	°C
T_{AMB}	Ambient temperature	Under bias	-65	135	°C
T_J	Junction temperature	PQFP, RQFP, TQFP, and BGA packages, under bias		135	°C
		Ceramic PGA packages, under bias		150	°C

Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 2 of 2) *Notes (2), (7), (8)*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{OL}	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)			0.45	V
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.00 V (11)			0.2	V
	3.3-V low-level PCI output voltage	I _{OL} = 1.5 mA DC, V _{CCIO} = 3.00 to 3.60 V (11)			0.1 × V _{CCIO}	V
	2.5-V low-level output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 2.30 V (11)			0.2	V
I _{OL} = 1 mA DC, V _{CCIO} = 2.30 V (11)				0.4	V	
I _{OL} = 2 mA DC, V _{CCIO} = 2.30 V (11)				0.7	V	
I _I	Input pin leakage current	V _I = 5.75 to -0.5 V	-10		10	μA
I _{OZ}	Tri-stated I/O pin leakage current	V _O = 5.75 to -0.5 V	-10		10	μA
I _{CC0}	V _{CC} supply current (standby) (All ESBs in power-down mode)	V _I = ground, no load, no toggling inputs, -1 speed grade (12)		10		mA
		V _I = ground, no load, no toggling inputs, -2, -3 speed grades (12)		5		mA
R _{CONF}	Value of I/O pin pull-up resistor before and during configuration	V _{CCIO} = 3.0 V (13)	20		50	W
		V _{CCIO} = 2.375 V (13)	30		80	W

All specifications are always representative of worst-case supply voltage and junction temperature conditions. All output-pin-timing specifications are reported for maximum driver strength.

Figure 36 shows the f_{MAX} timing model for APEX 20K devices.

Figure 36. APEX 20K t_{MAX} Timing Model

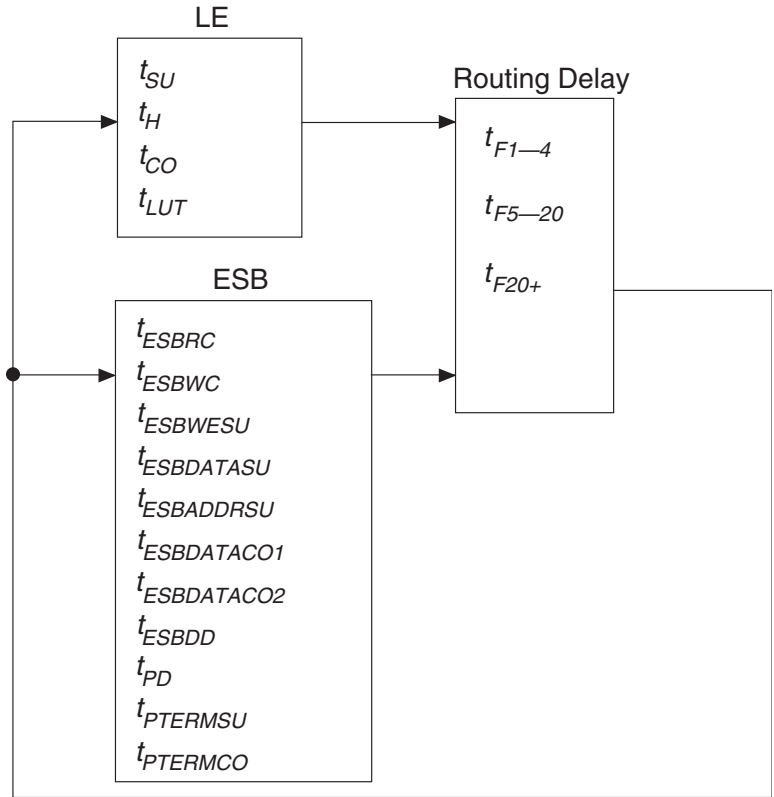


Figure 37 shows the f_{MAX} timing model for APEX 20KE devices. These parameters can be used to estimate f_{MAX} for multiple levels of logic. Quartus II software timing analysis should be used for more accurate timing information.

Table 46. EP20K200 External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}} (1)$	1.9		2.3		2.6		ns
$t_{\text{INHDIR}} (1)$	0.0		0.0		0.0		ns
$t_{\text{OUTCOBIDIR}} (1)$	2.0	4.6	2.0	5.6	2.0	6.8	ns
$t_{\text{XZBIDIR}} (1)$		5.0		5.9		6.9	ns
$t_{\text{ZXBIDIR}} (1)$		5.0		5.9		6.9	ns
$t_{\text{INSUBIDIR}} (2)$	1.1		1.2		–		ns
$t_{\text{INHDIR}} (2)$	0.0		0.0		–		ns
$t_{\text{OUTCOBIDIR}} (2)$	0.5	2.7	0.5	3.1	–	–	ns
$t_{\text{XZBIDIR}} (2)$		4.3		5.0		–	ns
$t_{\text{ZXBIDIR}} (2)$		4.3		5.0		–	ns

Table 47. EP20K400 External Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}} (1)$	1.4		1.8		2.0		ns
$t_{\text{INH}} (1)$	0.0		0.0		0.0		ns
$t_{\text{OUTCO}} (1)$	2.0	4.9	2.0	6.1	2.0	7.0	ns
$t_{\text{INSU}} (2)$	0.4		1.0		–		ns
$t_{\text{INH}} (2)$	0.0		0.0		–		ns
$t_{\text{OUTCO}} (2)$	0.5	3.1	0.5	4.1	–	–	ns

Table 48. EP20K400 External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}} (1)$	1.4		1.8		2.0		ns
$t_{\text{INHDIR}} (1)$	0.0		0.0		0.0		ns
$t_{\text{OUTCOBIDIR}} (1)$	2.0	4.9	2.0	6.1	2.0	7.0	ns
$t_{\text{XZBIDIR}} (1)$		7.3		8.9		10.3	ns
$t_{\text{ZXBIDIR}} (1)$		7.3		8.9		10.3	ns
$t_{\text{INSUBIDIR}} (2)$	0.5		1.0		–		ns
$t_{\text{INHDIR}} (2)$	0.0		0.0		–		ns
$t_{\text{OUTCOBIDIR}} (2)$	0.5	3.1	0.5	4.1	–	–	ns
$t_{\text{XZBIDIR}} (2)$		6.2		7.6		–	ns
$t_{\text{ZXBIDIR}} (2)$		6.2		7.6		–	ns

Table 57. EP20K60E f_{MAX} Routing Delays

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.24		0.26		0.30	ns
t_{F5-20}		1.45		1.58		1.79	ns
t_{F20+}		1.96		2.14		2.45	ns

Table 58. EP20K60E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	2.00		2.50		2.75		ns
t_{CL}	2.00		2.50		2.75		ns
t_{CLRP}	0.20		0.28		0.41		ns
t_{PREP}	0.20		0.28		0.41		ns
t_{ESBCH}	2.00		2.50		2.75		ns
t_{ESBCL}	2.00		2.50		2.75		ns
t_{ESBWP}	1.29		1.80		2.66		ns
t_{ESBRP}	1.04		1.45		2.14		ns

Table 59. EP20K60E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.03		2.12		2.23		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	4.84	2.00	5.31	2.00	5.81	ns
$t_{INSUPLL}$	1.12		1.15		-		ns
t_{INHPLL}	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	3.37	0.50	3.69	-	-	ns

Table 64. EP20K100E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	2.00		2.00		2.00		ns
t _{CL}	2.00		2.00		2.00		ns
t _{CLRP}	0.20		0.20		0.20		ns
t _{PREP}	0.20		0.20		0.20		ns
t _{ESBCH}	2.00		2.00		2.00		ns
t _{ESBCL}	2.00		2.00		2.00		ns
t _{ESBWP}	1.29		1.53		1.66		ns
t _{ESBRP}	1.11		1.29		1.41		ns

Table 65. EP20K100E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.23		2.32		2.43		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	4.86	2.00	5.35	2.00	5.84	ns
t _{INSUPLL}	1.58		1.66		-		ns
t _{INHPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	2.96	0.50	3.29	-	-	ns

Table 66. EP20K100E External Bidirectional Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.74		2.96		3.19		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	4.86	2.00	5.35	2.00	5.84	ns
t _{XZBIDIR}		5.00		5.48		5.89	ns
t _{ZXBIDIR}		5.00		5.48		5.89	ns
t _{INSUBIDIRPLL}	4.64		5.03		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	2.96	0.50	3.29	-	-	ns
t _{XZBIDIRPLL}		3.10		3.42		-	ns
t _{ZXBIDIRPLL}		3.10		3.42		-	ns

Tables 67 through 72 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K160E APEX 20KE devices.

Table 67. EP20K160E f_{MAX} LE Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.22		0.24		0.26		ns
t_H	0.22		0.24		0.26		ns
t_{CO}		0.25		0.31		0.35	ns
t_{LUT}		0.69		0.88		1.12	ns

Table 74. EP20K200E t_{MAX} ESB Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.68		2.06		2.24	ns
t_{ESBSRC}		2.27		2.77		3.18	ns
t_{ESBAWC}		3.10		3.86		4.50	ns
t_{ESBSWC}		2.90		3.67		4.21	ns
$t_{ESBWASU}$	0.55		0.67		0.74		ns
t_{ESBWAH}	0.36		0.46		0.48		ns
$t_{ESBWDSU}$	0.69		0.83		0.95		ns
t_{ESBWDH}	0.36		0.46		0.48		ns
$t_{ESBRASU}$	1.61		1.90		2.09		ns
t_{ESBRAH}	0.00		0.00		0.01		ns
$t_{ESBWESU}$	1.42		1.71		2.01		ns
t_{ESBWEH}	0.00		0.00		0.00		ns
$t_{ESBDATASU}$	-0.06		-0.07		0.05		ns
$t_{ESBDATAH}$	0.13		0.13		0.13		ns
$t_{ESBWADDRSU}$	0.11		0.13		0.31		ns
$t_{ESBRADDRSU}$	0.18		0.23		0.39		ns
$t_{ESBDATACO1}$		1.09		1.35		1.51	ns
$t_{ESBDATACO2}$		2.19		2.75		3.22	ns
t_{ESBDD}		2.75		3.41		4.03	ns
t_{PD}		1.58		1.97		2.33	ns
$t_{PTERMSU}$	1.00		1.22		1.51		ns
$t_{PTERMCO}$		1.10		1.37		1.09	ns

Table 75. EP20K200E t_{MAX} Routing Delays

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.25		0.27		0.29	ns
t_{F5-20}		1.02		1.20		1.41	ns
t_{F20+}		1.99		2.23		2.53	ns

Table 76. EP20K200E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.36		2.44		2.65		ns
t _{CL}	1.36		2.44		2.65		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.36		2.44		2.65		ns
t _{ESBCL}	1.36		2.44		2.65		ns
t _{ESBWP}	1.18		1.48		1.76		ns
t _{ESBRP}	0.95		1.17		1.41		ns

Table 77. EP20K200E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.24		2.35		2.47		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.12	2.00	5.62	2.00	6.11	ns
t _{INSUPLL}	2.13		2.07		-		ns
t _{INHPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	3.01	0.50	3.36	-	-	ns

Table 104. EP20K1500E f_{MAX} ESB Timing Microparameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.78		2.02		1.95	ns
t_{ESBSRC}		2.52		2.91		3.14	ns
t_{ESBAWC}		3.52		4.11		4.40	ns
t_{ESBSWC}		3.23		3.84		4.16	ns
$t_{ESBWASU}$	0.62		0.67		0.61		ns
t_{ESBWAH}	0.41		0.55		0.55		ns
$t_{ESBWDSU}$	0.77		0.79		0.81		ns
t_{ESBWDH}	0.41		0.55		0.55		ns
$t_{ESBRASU}$	1.74		1.92		1.85		ns
t_{ESBRAH}	0.00		0.01		0.23		ns
$t_{ESBWESU}$	2.07		2.28		2.41		ns
t_{ESBWEH}	0.00		0.00		0.00		ns
$t_{ESBDATASU}$	0.25		0.27		0.29		ns
$t_{ESBDATAH}$	0.13		0.13		0.13		ns
$t_{ESBWADDRSU}$	0.11		0.04		0.11		ns
$t_{ESBRADDRSU}$	0.14		0.11		0.16		ns
$t_{ESBDATACO1}$		1.29		1.50		1.63	ns
$t_{ESBDATACO2}$		2.55		2.99		3.22	ns
t_{ESBDD}		3.12		3.57		3.85	ns
t_{PD}		1.84		2.13		2.32	ns
$t_{PTERMSU}$	1.08		1.19		1.32		ns
$t_{PTERMCO}$		1.31		1.53		1.66	ns

Table 105. EP20K1500E f_{MAX} Routing Delays

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.28		0.28		0.28	ns
t_{F5-20}		1.36		1.50		1.62	ns
t_{F20+}		4.43		4.48		5.07	ns